



Generate Collection

L35: Entry 61 of 61

File: DWPI

Feb 20, 1975

DERWENT-ACC-NO: 1975-14614W

DERWENT-WEEK: 197509

COPYRIGHT 2002 DERWENT INFORMATION LTD

TITLE: Soft solder contacts for integrated circuits - chips coated with aluminium, then electroless
nickel plated and solder-dipped

PATENT-ASSIGNEE:

ASSIGNEE

CODE

SIEMENS AG

SIEI

PRIORITY-DATA: 1973DE-2340423 (August 9, 1973), 1975DE-2522773 (May 22, 1975)

PATENT-FAMILY:

PUB-NO

PUB-DATE

LANGUAGE

PAGES

MAIN-IPC

DE 2340423 A

February 20, 1975

000

INT-CL (IPC): H01L 21/18; H01L 23/48

ABSTRACTED-PUB-NO: DE 2340423A

BASIC-ABSTRACT:

At least part of one surface of a slice is coated with (a) a layer of Al, pref. 6 μ m thick, then (b) nickel, pref. contg. 1-10 wt. % Cu and 1 μ m thick by electroless plating; and (c) a low m.pt. solder pref. 50 μ m thick by solder-dipper. The advantages are a lower saturation voltage, lower heat losses, and a higher surge current tolerance due to the heat-capacity of the lead in the solder; furthermore the process can be standardised and automated.

TITLE-TERMS: SOFT SOLDER CONTACT INTEGRATE CIRCUIT CHIP COATING ALUMINIUM ELECTROLESS NICKEL PLATE
SOLDER DIP

DERWENT-CLASS: L03 U11 U12

CPI-CODES: L03-D03D;